



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-05-05
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SMAJ6.0A-TR	8HST*TWUV70C	A	BOUSKOURA B/E	2016-05-05
Amount		UoM	Unit type	ST ECOPACK Grade
70.00		mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SOJ	4.14-2.76-1.94	2	J BEND	
Comment	SMA			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	8HST*TWUV70C					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.111	mg	supplier	die	Silicon (Si)	7440-21-3		1.092	mg	982898	15600
				supplier	metallization	Aluminium (Al)	7429-90-5		0.003	mg	2700	43
				supplier	Passivation	Silicon Oxide	7631-86-9		0.004	mg	3600	57
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.004	mg	3600	57
				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	900	14
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.007	mg	6302	100
Leadframe	Copper & its alloys	30.254	mg	supplier	alloy	Copper (Cu)	7440-50-8		29.767	mg	983903	425243
				supplier	alloy	Iron (Fe)	7439-89-6		0.030	mg	992	429
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.009	mg	297	129
				supplier	metallization	Nickel (Ni)	7440-02-0		0.445	mg	14709	6357
				supplier	metallization	Phosphorus (P)	12185-10-3		0.003	mg	99	43
				supplier	metallization	Phosphorus (P)	12185-10-3		0.003	mg	99	43
Soft solder	Solder	1.135	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	1.061	mg	934802	15157
				supplier	solder	Tin (Sn)	7440-31-5		0.057	mg	50220	814
				supplier	solder	Silver (Ag)	7440-22-4		0.017	mg	14978	243
Encapsulation	Other Organic Materials	25.278	mg	supplier	mold compound	Silica, vitreous	60676-86-0		19.211	mg	759989	274443
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		2.578	mg	101986	36829
				supplier	mold compound	Phenol resin	9003-35-4		1.517	mg	60013	21671
				supplier	mold compound	Others	Proprietary		1.264	mg	50004	18057
				supplier	mold compound	Metal hydroxide	21645-51-2		0.506	mg	20017	7229
				supplier	mold compound	Carbon black	1333-86-4		0.202	mg	7991	2886
Connections coating	Solder	0.741	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.741	mg	1000000	10586
Clip	Copper & its alloys	11.481	mg	supplier	alloy	Copper (Cu)	7440-50-8		11.481	mg	1000000	164014